

A satellite-style map of the world with a network of glowing yellow and green lines connecting various points across the continents, representing a global communication or data network.

HIGH-END (OPTO)ELECTRONICS FOR DATA- AND TELECOM INDUSTRY

YOUR EUROPEAN PACKAGING AND TECHNOLOGY PARTNER

AEMtec provides a complete range of custom integrated packaging solutions for the communication market. We will support you in all phases of development - from concept development, co-product- and process development, qualification and serial production (incl. supply chain management) to annual quantities from 50pcs - 1 million at our main manufacturing facility in Berlin, Germany.

TECHNOLOGIES & SERVICES

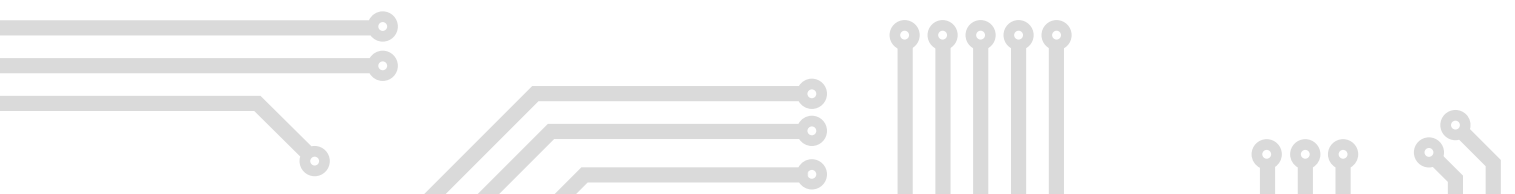
- High reliable active and passive optical alignment
- Advanced packaging (Flip Chip, COB, SMD)
- Die placement accuracy of <math><1\mu</math>
- In-house test engineering department
- Industrialization of high-sophisticated (opto) electronic modules
- Process transfer

QUALITY & TESTING

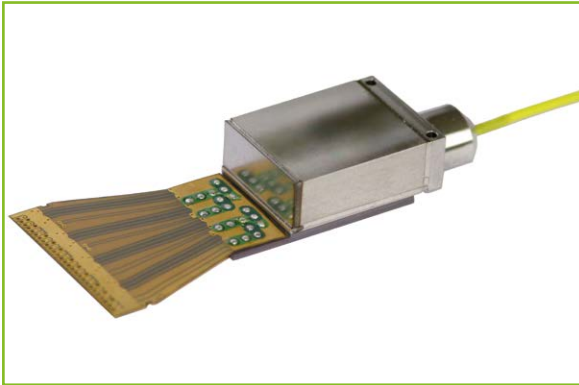
- Full scale traceability and yield management
- Audited by leading OEMs from the data and telecom industry
- Electrical tests (ICT, FCT, Boundary Scan, Flying probe)
- Environmental tests (HTOL, THS, TCT, HTS, shock and vibration test)
- Process- & product qualification (Telcordia, MIL, etc.)
- Analysis technology (x-section, SAM, μ -scan, AOI, AXI)

MAJOR APPLICATIONS

- MCM for 10/40 GBit data transmission
- SIP
- Subsystem for xSFP connectors
- Lens arrays
- 2,5D / 3D-Packages
- WLP



COMPLEX AND ADVANCED MICRO-ELECTRONIC SYSTEMS



SERVICES

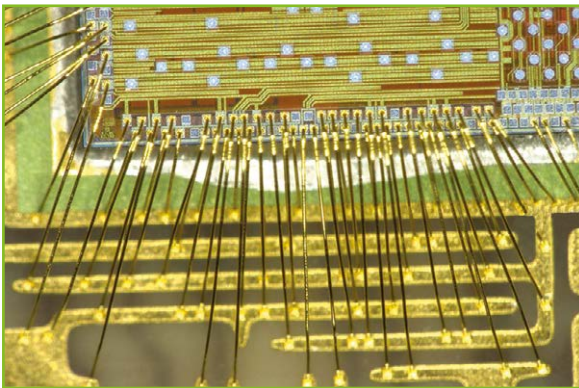
Feasibility study • Chip-Design support • Layout and design • Package technology • Design support • Thermal simulation

TECHNOLOGY

Flex soldering • Placement accuracy of photodiode $\pm 1\mu\text{m}$ • Dicaps & Chipresistors accuracy of $\pm 20\mu\text{m}$ • Exact wire bond loops, $23\mu\text{m}$ wire

VOLUME SUPPLY

Worldwide deliveries • All common logistic models • Certified OEM partner for assembly



SERVICES

Layout and design • Prototyping • Process qualification • Volume production

TECHNOLOGY

Au-Bonden (stand-off stich) • $23\mu\text{m}$ bond wires • $60\mu\text{m}$ Bondpad-Pitch • Bondpads $50\mu\text{m}$ and 3-rows on IC • 320 wire bonds

VOLUME SUPPLY

Complete supply chain management • Worldwide deliveries



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